

XPedite7575

End of Life

5th Generation Intel® Core™ i7 Broadwell-H Processor-Based Conduction- or Air-Cooled 3U VPX-REDI Module **Please contact X-ES Sales**

- ▶ Supports 5th generation (Broadwell-H) and 4th generation (Haswell) Intel® Core™ i7 processors
- ▶ 3U VPX (VITA 46) module
- ▶ OpenVPX™ standards based
- ▶ VITA 66.4 fiber optic connector
- ▶ Ruggedized Enhanced Design Implementation (REDI) per VITA 48
- ▶ Conduction or air cooling
- ▶ Up to 8 GB of DDR3 ECC SDRAM in two channels
- ▶ Up to 32 GB of NAND flash
- ▶ XMC interface
- ▶ Two PCI Express Fat Pipe P1 fabric interconnects
- ▶ Three Gigabit Ethernet ports
- ▶ Two SATA ports
- ▶ One DisplayPort interface
- ▶ One XMC (P16) SATA port for storage mezzanine
- ▶ Intel® vPro™/AMT support
- ▶ VITA 46.11 Tier 2 IPMI support
- ▶ Wind River VxWorks BSP
- ▶ X-ES Enterprise Linux (XEL) BSP
- ▶ Microsoft Windows drivers
- ▶ Contact factory for availability of Green Hills INTEGRITY, QNX Neutrino, and LinuxWorks LynxOS BSPs



XPedite7575

The XPedite7575 is a high-performance, 3U VPX-REDI, single board computer based on the 5th generation Intel® Core™ i7 Broadwell-H processor. The XPedite7575 maximizes network performance with three Gigabit Ethernet interfaces, configured as two 1000BASE-BX/KX (SerDes) ports and one 10/100/1000BASE-T port. An integrated PCI Express switch with Non-Transparent Bridging support enables direct communication with other Intel® processors, eliminating the need for a separate switch module within the system and further reducing SWaP-C for the system integrator.

The XPedite7575 provides superior growth and expansion capabilities by including an XMC site with full 10 mm I/O envelope support, while maintaining a 0.8 in. VPX slot pitch and providing the system integrator with a plethora of COTS options for additional I/O, storage, or processing, all while minimizing total system SWaP-C. Additionally, the XPedite7575 provides significant maintenance and diagnostics advantages by including optimized Two-Level Maintenance (2LM) metalwork and enabling the remote configuration and management capabilities of Intel® vPro™ with Intel® Active Management Technology (Intel® AMT) support. The XPedite7575 leverages Intel® Iris™ Pro graphics for graphics-intensive applications and serves as a general-purpose GPU for demanding data processing applications.

The XPedite7575 accommodates up to 8 GB of DDR3 ECC SDRAM in two channels to support memory-intensive applications. The XPedite7575 also hosts numerous I/O ports, including PCI Express, Gigabit Ethernet, USB, SATA, graphics, and RS-232/422/485 through the backplane connectors. Wind River VxWorks and X-ES Enterprise Linux (XEL) Board Support Packages (BSPs) are available, as well as Microsoft Windows drivers.

X-ES

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...Always Fast

Extreme Engineering Solutions

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Processor

- 5th generation Intel® Core™ i7 (Broadwell-H)
- 4th generation Intel® Core™ i7 (Haswell)
- Integrated high-performance 3D graphics controller
- Up to Intel® Iris™ Pro Graphics 6200

Memory

- Up to 8 GB of DDR3 ECC SDRAM in two channels
- Up to 32 GB of NAND flash
- 64 MB NOR boot flash
- 64 kB EEPROM

VPX (VITA 46) P0 I/O

- VITA 46.11 Tier 2 IPMI controller (IPMC)
- 1 Pulse Per Second (1PPS)

VPX (VITA 46) P1 I/O

- x4 PCI Express Fat Pipe interface to P1.A
- x4 PCI Express Fat Pipe interface to P1.B
- Two 1000BASE-BX/KX Gigabit Ethernet ports
- XMC P16 I/O, mapping P1w9-X12d per VITA 46.9
- 3.3 V GPIO signals

VPX (VITA 46) P2 I/O

- One 10/100/1000BASE-T Gigabit Ethernet port
- Two SATA ports capable of 6 Gb/s
- Two USB 2.0 ports
- One DisplayPort interface
- One RS-232/422/485 serial port

XMC Site

- x8 PCI Express Gen3-capable port
- One SATA port capable of 6 Gb/s

Additional Features

- Non-volatile memory write protection
- Optional Trusted Platform Module (TPM)
- IEEE 1588 support on two Gigabit Ethernet ports
- Intel® Active Management Technology (AMT) supported by Intel® vPro™ Technology

Software Support

- Wind River VxWorks BSP
- X-ES Enterprise Linux (XEL) BSP
- Microsoft Windows drivers
- Contact factory for availability of Green Hills INTEGRITY, QNX Neutrino, and LynuxWorks LynxOS BSPs

Physical Characteristics

- 3U VPX-REDI conduction- or air-cooled form factor
- Dimensions: 100 mm x 160 mm
- 0.8 in. pitch without solder-side cover
- 0.85 in. and 1.0 in. pitch with solder-side cover
- Optional Two-Level Maintenance (2LM) metalwork (1.0 in. pitch)

Environmental Requirements

Contact factory for appropriate board configuration based on environmental requirements.

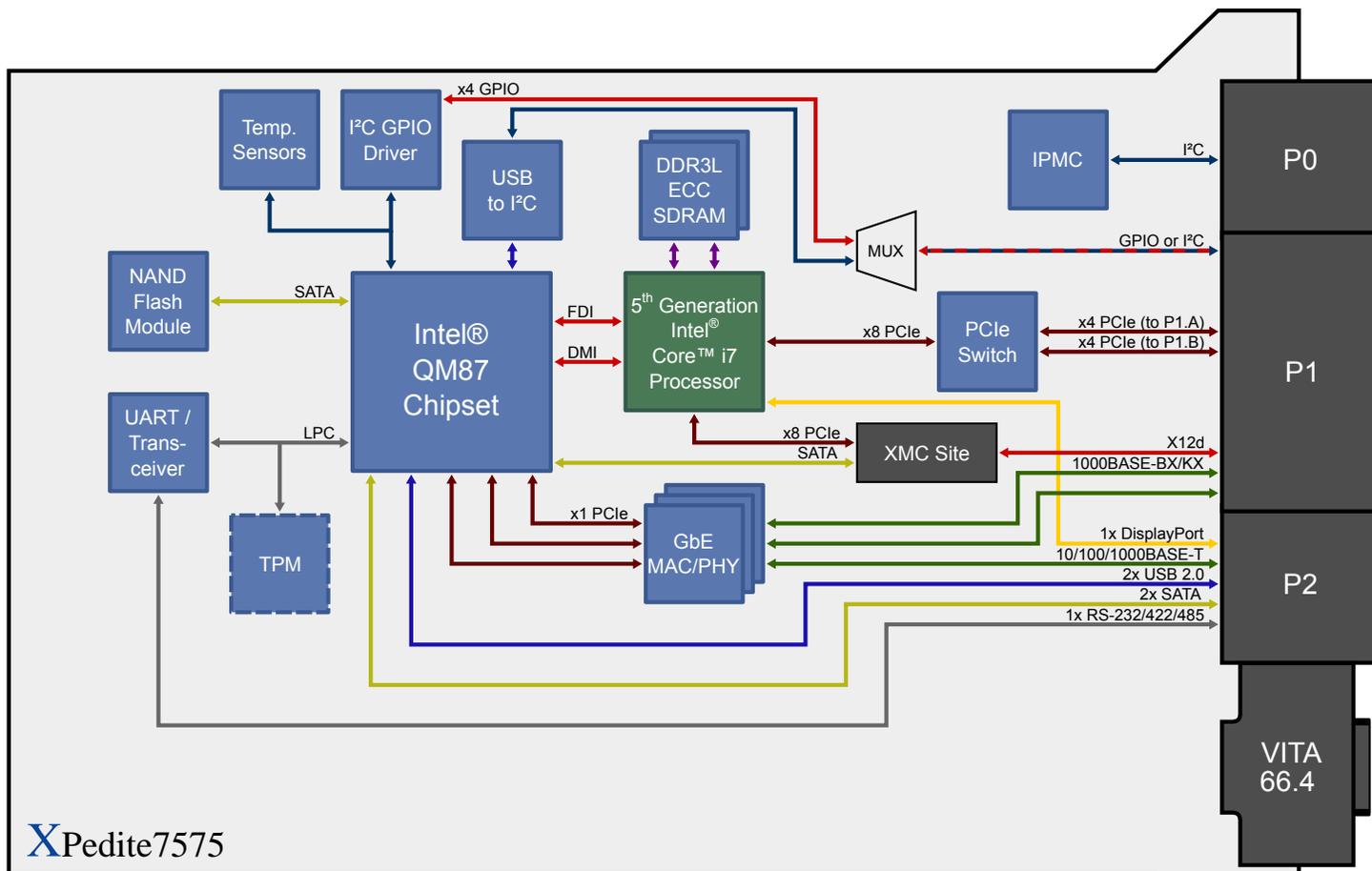
- Supported ruggedization levels (see chart below): 1, 3, 5
- Conformal coating available as an ordering option
- Thermal performance will vary based on CPU frequency and application

Power Requirements

- Power will vary based on configuration and usage. Please consult factory.

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient †	-40 to +70°C ambient †	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C (maximum)
Vibration	0.002 g ² /Hz (maximum), 5 to 2000 Hz	0.04 g ² /Hz (maximum), 5 to 2000 Hz	0.1 g ² /Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	Up to 95% non-condensing	Up to 95% non-condensing	Up to 95% non-condensing

† Contact factory for airflow rate details.



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